

ABSTRACT

The present invention relates to: a resin composition containing (A) a thermosetting resin, (B) one or more selected from the group consisting of a conjugated diene polymer and its derivative, having 2 or more of a functional group including an ethylenically unsaturated bond, and (C) an inorganic filler whose surface is treated with a silane coupling agent having a functional group including an ethylenically unsaturated bond; and a prepreg, a laminate, a resin film, a printed wiring board, and a semiconductor package, all of which use the said resin composition.